

# 8329TCM



## Heatsink Adhesive

8329TCM is a 2-part thermally conductive epoxy adhesive. It is a dark grey, smooth, thixotropic paste that cures to form a hard, durable polymer that is thermally conductive, yet electrically insulating.

This adhesive is most often used as heatsink glue, attaching heatsinks to CPUs, LEDs, or other heat generating electronics components.

This compound has been formulated for high thermal conductivity. It is highly viscous and must be mixed by hand prior to application. For a lower viscosity use 8349TFM. For a shorter working time, use 8349TFM. For a longer working time, use 8329TCS.



## Features & Benefits

- High thermal conductivity
- 1:1 mix ratio
- Provides strong electrical insulation
- Bonds well to a wide variety of substances
- Strong resistance to humidity, salt water, mild bases, and aliphatic hydrocarbons

## Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
8329TCM-6ML	2 Syringe Kit	6 mL	14.8 g
8329TCM-50ML	2 Jar Kit	50 mL	121 g

## Contact Information

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## Cured Properties

Resistivity	$9 \times 10^{12} \Omega \cdot \text{cm}$
Hardness	77 D
Tensile Strength	10 N/mm <sup>2</sup>
Compressive Strength	34 N/mm <sup>2</sup>
Lap Shear (stainless steel)	6.4 N/mm <sup>2</sup>
(aluminum)	6.1 N/mm <sup>2</sup>
Glass Transition Temperature (T <sub>g</sub> )	46 °C
CTE Prior T <sub>g</sub>	71 ppm/°C
CTE After T <sub>g</sub>	131 ppm/°C
Thermal Conductivity @ 25 °C	1.4 W/(m·K)
Service Temperature Range	-40–150 °C

## Usage Parameters

Working Time	45 min
Mix Ratio by Volume	1:1
Mix Ratio by Weight	0.93:1

## Uncured Properties

Mixed Density	2.41 g/mL
Viscosity @ 25 °C	(A) 780 Pa·s
	(B) 810 Pa·s

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## Application Instructions

Read the product SDS and Application Guide for more detailed instructions before using this product (downloadable at [www.mgchemicals.com](http://www.mgchemicals.com)).

## Recommended Preparation

Clean the substrate with Isopropyl Alcohol, MG #824, so the surface is free of oils, dust, and other residues.

## Syringe

1. Twist and remove the cap from the syringe. Do not discard cap.
2. Measure 1 part by volume of A.
3. Measure 1 part by volume of B.
4. Dispense material on a mixing surface or container, and thoroughly mix parts A and B together.
5. To stop the flow, pull back on the plunger.
6. Clean nozzle to prevent contamination and material buildup.
7. Replace the cap on the syringe.

## Can or Jar

1. Stir each part individually to re-incorporate material that may have separated during storage.
2. Measure 0.93 part by weight of A.
3. Measure 1 part by weight of B.
4. Thoroughly mix parts A and B together.
5. Apply adhesive to the application area.

## Cure Instructions

Allow to cure at room temperature for 24 hours, or cure the adhesive in an oven at one of these time/temperature options:

<b>Temperature</b>	65 °C	80 °C	100 °C
<b>Time</b>	1 hour	45 minutes	20 minutes

## Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight (see SDS). To maximize shelf life, recap product firmly when not in use.

## Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.